

VERY LOW CONSUMPTION CURRENT.
VOLTAGE DETECTOR ICs.

Function of this IC is accurately resetting the system after detecting voltage at the time of switching power on and instantaneous power off in various CPU systems and other logic systems.

FEATURES

- Current Consumption is Low. $I_{CCL}=100\mu A$ Typ. $I_{CCH}=1.0\mu A$ Typ.
- Resetting Output Minimum Guarantee Voltage is Low 0.8V Typ.
- Hysteresis Voltage is Provided. 50mV Typ.
- Reset Signal Generation Starting Voltages:

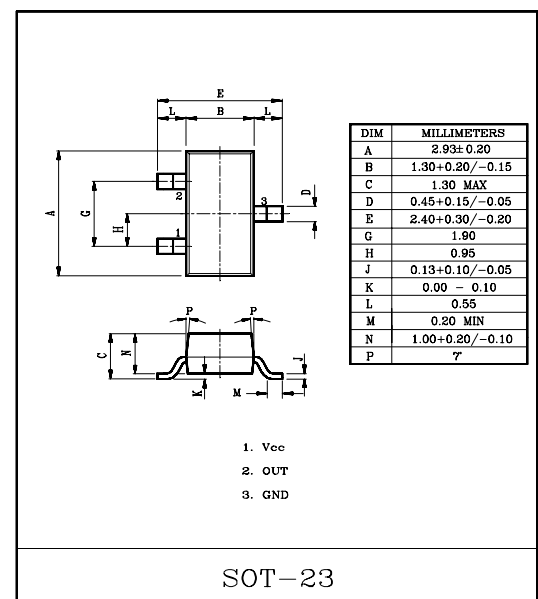
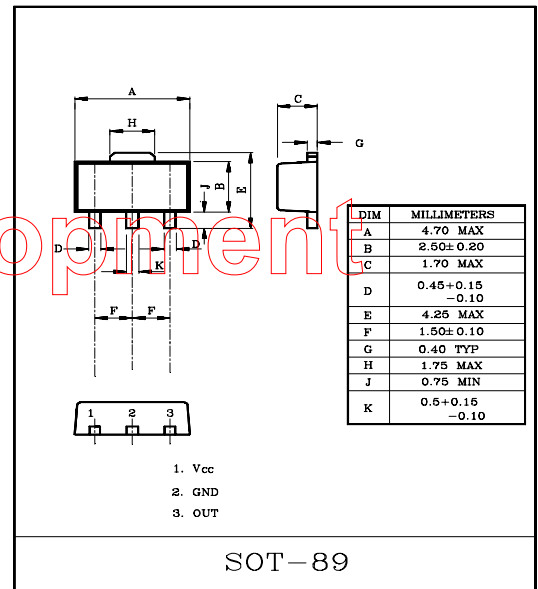
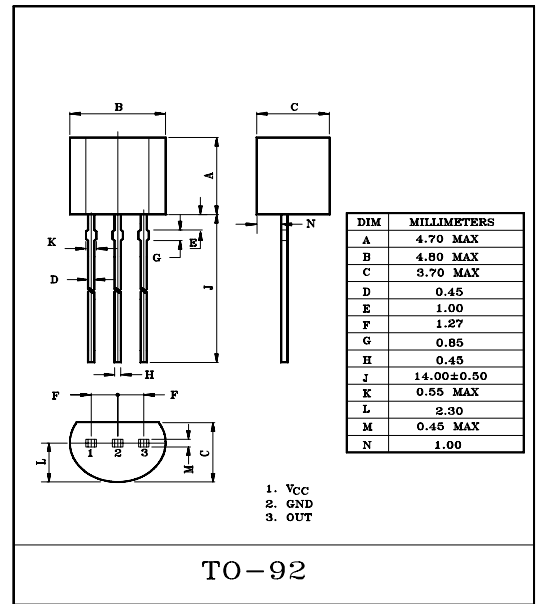
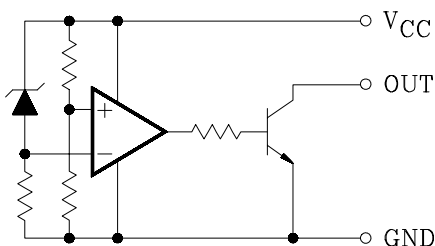
KIA7219P/F/S	1.9V Typ.	KIA7233P/F/S	3.3V Typ.
KIA7221P/F/S	2.1V Typ.	KIA7234P/F/S	3.4V Typ.
KIA7223P/F/S	2.3V Typ.	KIA7235P/F/S	3.5V Typ.
KIA7225P/F/S	2.5V Typ.	KIA7236P/F/S	3.6V Typ.
KIA7227P/F/S	2.7V Typ.	KIA7239P/F/S	3.9V Typ.
KIA7229P/F/S	2.9V Typ.	KIA7242P/F/S	4.2V Typ.
KIA7231P/F/S	3.1V Typ.	KIA7245P/F/S	4.5V Typ.
KIA7232P/F/S	3.2V Typ.		

MARKING

Type No.	$V_{S(Typ)}$ (V)	Marking	Type No.	$V_{S(Typ)}$ (V)	Marking
KIA7219	1.9	2A 72A	KIA7233	3.3	2J 72J
KIA7221	2.1	2B 72B	KIA7234	3.4	2K 72K
KIA7223	2.3	2C 72C	KIA7235	3.5	2L 72L
KIA7225	2.5	2D 72D	KIA7236	3.6	2M 72M
KIA7227	2.7	2E 72E	KIA7239	3.9	2N 72N
KIA7229	2.9	2F 72F	KIA7242	4.2	2P 72P
KIA7231	3.1	2G 72G	KIA7245	4.5	2R 72R
KIA7232	3.2	2H 72H			

Note) F : SOT-89 / S : SOT-23

EQUIVALENT CIRCUIT



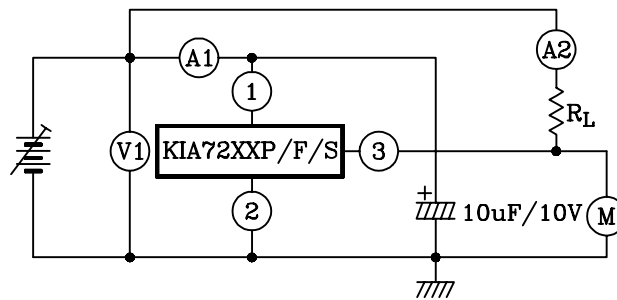
MAXIMUM RATINGS (Ta=25°C)

CHARACTERISTIC		SYMBOL	RATING	UNIT
Supply Voltage		V_{CC}	-0.3 ~ +10.0	V
Power Dissipation (Package Limitation)	KIA7219P~45P	P_D	400	mW
	KIA7219F~45F		500	
	KIA7219S~45S		350	
Operating Temperature		T_{opr}	-30 ~ +75	°C
Storage Temperature		T_{stg}	-55 ~ +150	°C

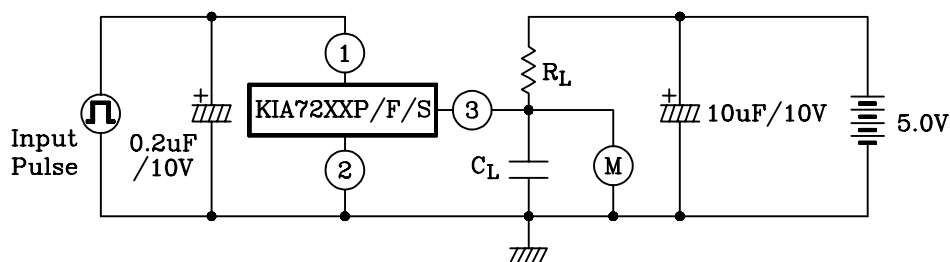
ELECTRICAL CHARACTERISTICS

CHARACTERISTIC	SYMBOL	TEST CIR.	TEST CONDITION		MIN.	TYP.	MAX.	UNIT
Detecting Voltage	V_S	1	$R_L=470\Omega$ $V_{OL} \leq 0.4V$	KIA7219P/F/S KIA7221P/F/S KIA7223P/F/S KIA7225P/F/S KIA7227P/F/S KIA7229P/F/S KIA7231P/F/S KIA7232P/F/S KIA7233P/F/S KIA7234P/F/S KIA7235P/F/S KIA7236P/F/S KIA7239P/F/S KIA7242P/F/S KIA7245P/F/S	1.75 1.95 2.15 2.35 2.55 2.75 2.95 3.05 3.15 3.25 3.35 3.45 3.75 4.05 4.35	1.9 2.1 2.3 2.5 2.7 2.9 3.1 3.2 3.3 3.4 3.5 3.6 3.9 4.2 4.5	2.05 2.25 2.45 2.65 2.85 3.05 3.25 3.35 3.45 3.55 3.65 3.75 4.05 4.35 4.65	V
Low-Level Output Voltage	V_{OL}	1	$R_L=470\Omega$		-	-	0.4	V
Output Leakage Current	I_{OH}	1	$V_{CC}=10V$		-	-	0.1	μA
Hysteresis Voltage	ΔV_S	1	$R_L=470\Omega$		30	50	100	mV
Detecting Voltage Temperature Coefficient	$V_S/\Delta T$	1	$R_L=470\Omega$		-	± 0.01	-	%/°C
Circuit Current at on Time	I_{ccL}	1	$V_{CC}=V_{Smin.}-0.05V$		-	100	150	μA
Circuit Current at off Time	I_{ccH}	1	$V_{CC}=V_{Smax}+0.1V$		-	1.0	2.5	μA
Threshold Operating Voltage	V_{opr}	1	$R_L=4.7k\Omega$, $V_{OL} \leq 0.4V$		-	0.8	-	V
"L" Transmission Delay Time	t_{pHL}	2	$R_L=4.7k\Omega$, $C_L=100pF$		-	10	-	μS
"H" Transmission Delay Time	t_{pLH}	2	$R_L=4.7k\Omega$, $C_L=100pF$		-	15	-	μS
Output Current at on Time I	$I_{oL I}$	1	$V_{CC}=V_{Smin.}-0.05V$ $T_c=25^\circ C$		15	-	-	mA
Output Current at on Time II	$I_{oL II}$	1	$V_{CC}=V_{Smin.}-0.05V$ $T_c=-30 \sim +75^\circ C$		7	-	-	mA

TEST CIRCUIT 1.

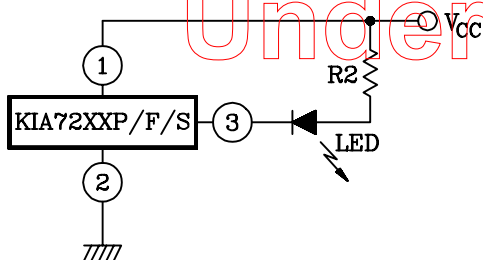


TEST CIRCUIT 2.

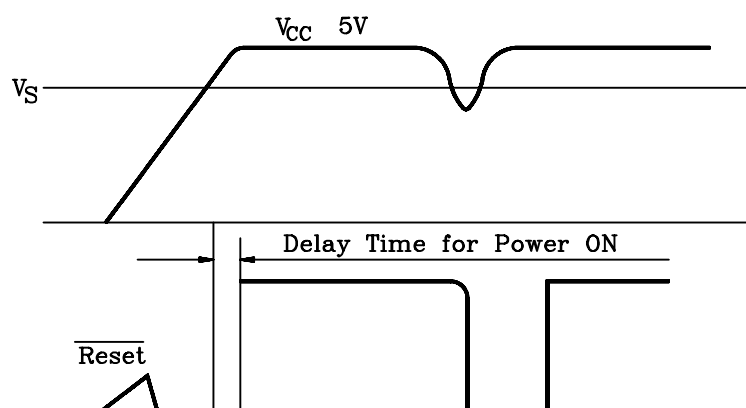
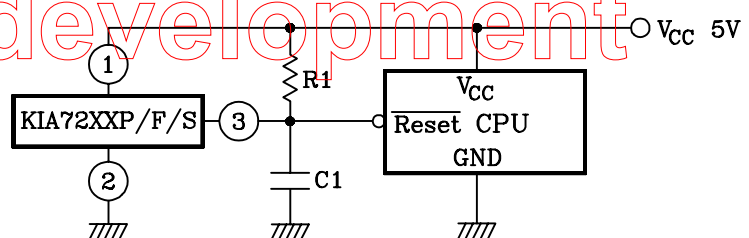


APPLICATION CIRCUIT

(1) BATTERY LOW INDICATOR



(2) CPU RESETTING



(NOTE)

- (1) Connecting of LED and R2 obtains a voltage drop indicator.
- (2) Connecting of C1 and selection of time constant with C1 and R1 set the power on delay time.

PRECAUTION FOR USE

SOLDERING

Flat Package (SOT-89/SOT-23 Package)

Elements mounting styles of electronic devices are gaining in further diversification over recent years, and needs for components are all the more expanding in varieties. Especially, surface mounting is steadily penetrating into industrial segments as a world-wide popular technical trend. Although exposure to high temperature is inevitable during soldering we recommend limiting the soldering temperature to low levels as shown in figure for the sake of retaining inherent excellent reliability.

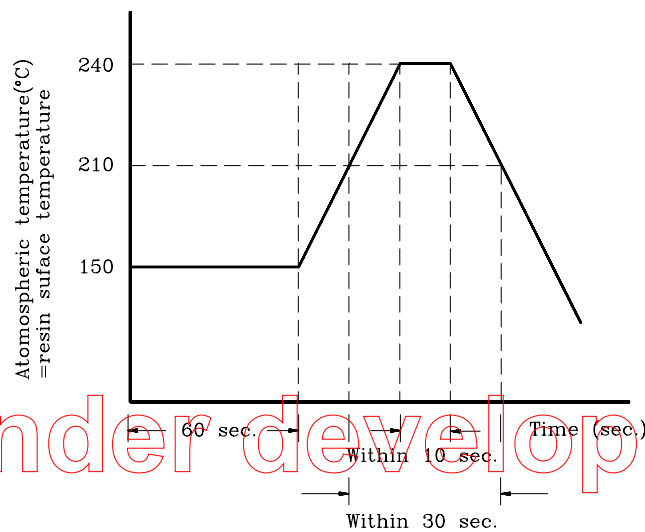


Fig 6

(a) When employing solder reflow method

- ① Atmospheric temperature around resin surfaces must be less than 240°C, not exceeding the time length of 10 sec.
- ② Recommend temperature profile
- ③ Precautions on heating method

When resin is kept exposed to high temperature for a long time, device reliability may be marred. Therefore, it is essential to complete soldering in the shortest time possible to prevent temperature of resin from rising.

(b) When employing halogen lamps or infrared-ray heaters

When halogen lamps or infrared-ray heaters are used, avoid direct irradiation onto resin surfaces; such devices cause extensive localized temperature rise.

※ Please keep a reflow solder operating when SOT-89/SOT-23 package's soldering.